

## **CHALLENGE SERIES DIAMOND SLURRIES**

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**CHALLENGE Series Diamond Slurries** are composed of an aqueous based synthetic formulation developed to optimize removal rate and surface finish when lapping or polishing metal, ceramic and optical material using either a lapping plate or a polishing pad. The slurries are fully suspended and dispersed for easy application from the slurry tank to the workpiece via a peristaltic pump.

The product also contains extra lubricating qualities for difficult processes. The extra lubrication allows for use of higher speeds and pressures. Exceptionally accurate finishes can be achieved down to a polished defect free finish.

Particle sizes are available from 0.5um to 60um and are chosen dependent upon surface roughness and removal rate required. When purchasing a CHALLENGE Series Diamond Slurry, please specify diamond size and either natural or synthetic diamond or consult a sales engineer.

### **Typical Applications:**

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Lapping or polishing a variety of metal, ceramic and optical material.

### **Benefits:**

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- Better surface finishes
- Faster removal rates
- High lubrication
- Low foam
- Non-staining
- Contains no glycols or oils
- Non-corrosive to ferrous metals

### **Typical Properties:**

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pH	9.3
Conductivity mS	0.325
Specific Gravity	1.01

### **Directions:**

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CHALLENGE Series Diamond Slurries are designed for use as received. The flow rate is determined by the size of the plate/pad and configuration of the plate/pad.

### **Additional Information:**

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CHALLENGE Series Diamond Slurries are available in 1-gallon bottles, 2 ½ gallon bottles and 5-gallon pails. Safety Data Sheets available upon request.